



Desemicon

D2300

20V N-Channel Enhancement Mode MOSFET

VDS= 20V

RDS(ON), Vgs@ 4.5V, Ids@ 3.6A <70mΩ

RDS(ON), Vgs@ 2.5V, Ids@ 3.1A <80mΩ

Features

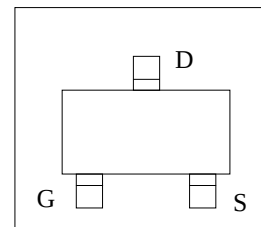
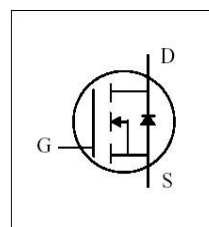
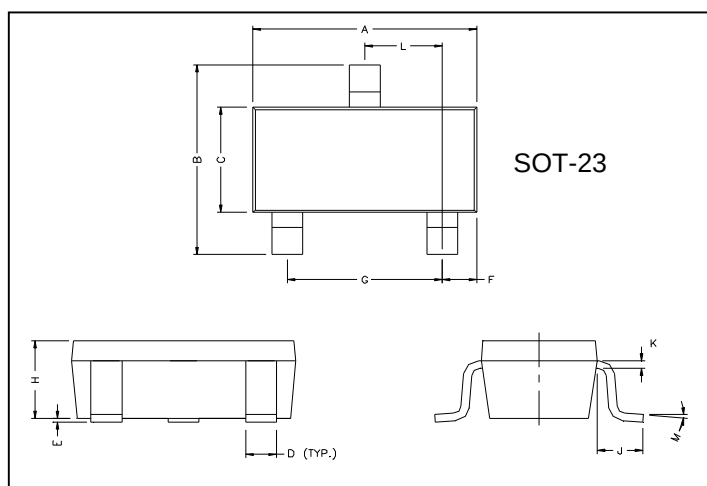
Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

High Power and Current handling capability

Ideal for Li ion battery pack applications

Package Dimensions



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.80	3.00	G	1.80	2.00
B	2.30	2.50	H	0.90	1.1
C	1.20	1.40	K	0.10	0.20
D	0.30	0.50	J	0.35	0.70
E	0	0.10	L	0.92	0.98
F	0.45	0.55	M	0°	10°

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	20	V
Gate-Source Voltage		V _{GS}	± 12	
Continuous Drain Current		I _D	3.6	A
Pulsed Drain Current ¹⁾		I _{DM}	8	
Maximum Power Dissipation	TA = 25°C	P _D	1.25	W
	TA = 75°C		0.8	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted) ²⁾		R _{θJA}	78	°C/W

Notes

¹⁾ Pulse width limited by maximum junction temperature.

²⁾ Surface Mounted on FR4 Board, t ≤ 5 sec.



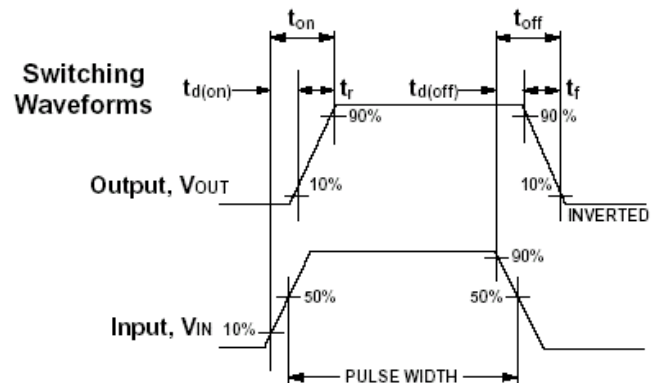
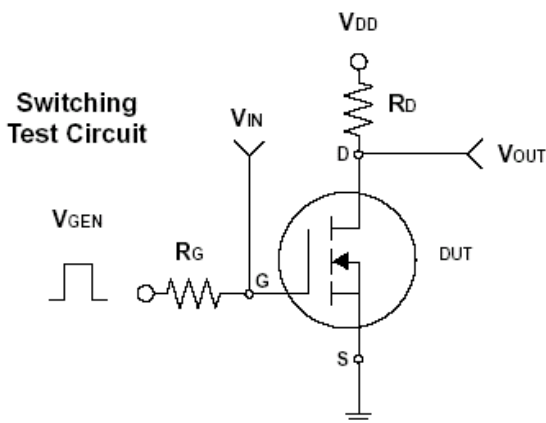
ELECTRICAL CHARACTERISTICS (TA = 25°C unless otherwise noted)

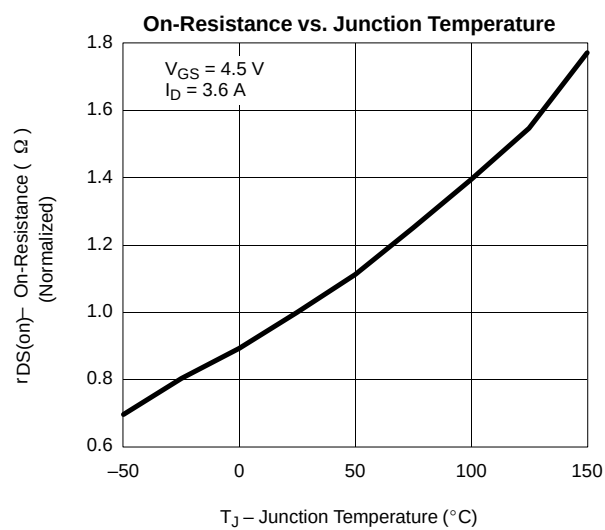
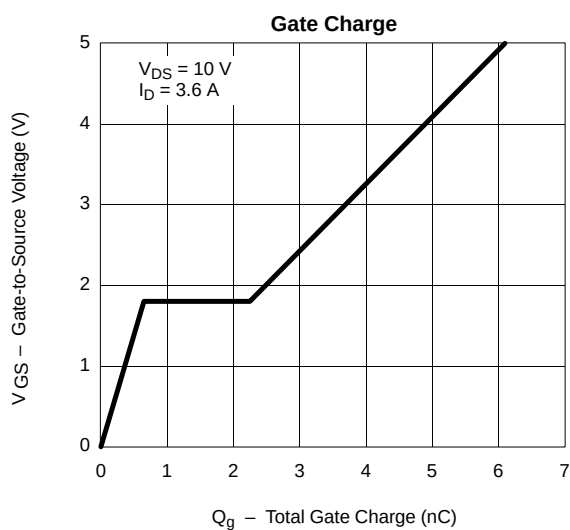
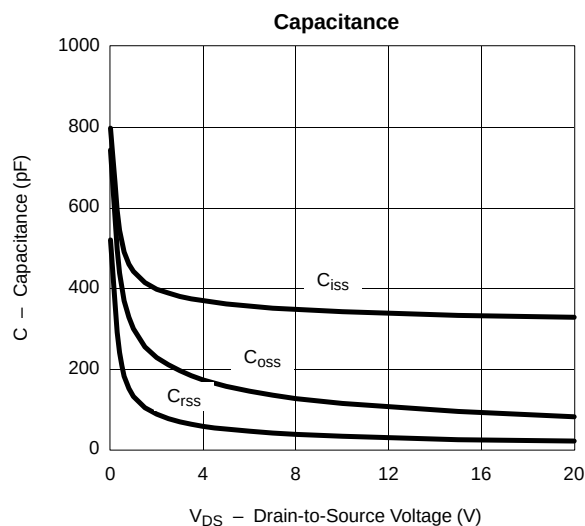
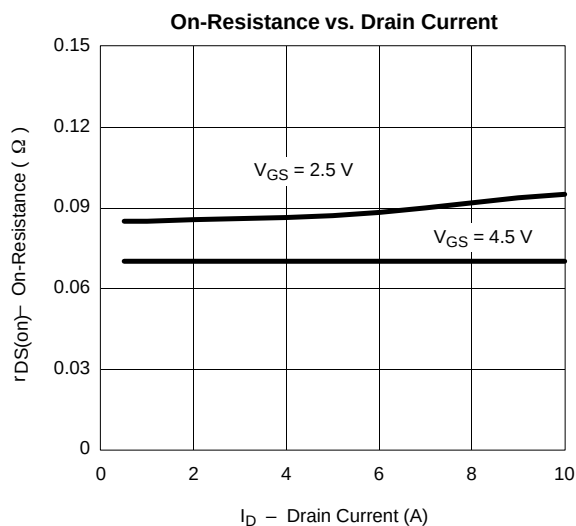
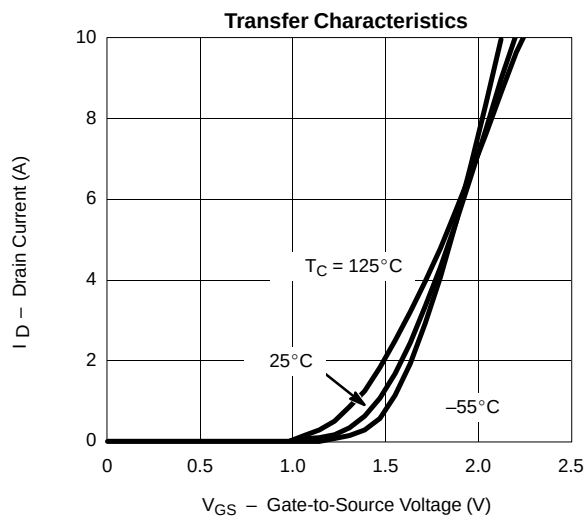
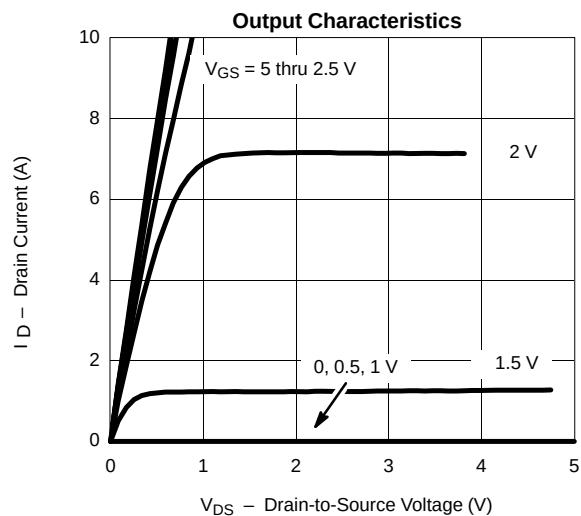
Parameter	Symbol	Test Condition	Min.	Typ.	Miax.	Unit
Static ³⁾						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250uA	20			V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 2.5V, I _D = 3.1A		70.0	80.0	mΩ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 3.6A		60.0	70.0	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D = 250uA	0.6	0.76		V
Zero Gate Voltage Drain Current 0	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	uA
Gate Body Leakage	I _{GSS}	V _{GS} = ± 12V, V _{DS} = 0V			±100	nA
Forward Transconductance	g _{fs}	V _{DS} = 5V, I _D = 4.2A		5	—	S
Dynamic ⁴⁾						
Total Gate Charge	Q _g	V _{DS} = 10V, I _D = 3.6A V _{GS} = 4.5V		5.4	10	nC
Gate-Source Charge	Q _{gs}			0.65		
Gate-Drain Charge	Q _{gd}			1.5		
Turn-On Delay Time	t _{d(on)}	V _{DD} = 10V, R _G = 6Ω I _D = 1A, V _{GS} = 4.5V RL = 5.5Ω		12	25	ns
Turn-On Rise Time	t _r			36	60	
Turn-Off Delay Time	t _{d(off)}			34	60	
Turn-Off Fall Time	t _f			10	25	
Input Capacitance	C _{iss}	V _{DS} = 10V, V _{GS} = 0V f = 1.0 MHz		340		pF
Output Capacitance	C _{oss}			115		
Reverse Transfer Capacitance	C _{rss}			33		
Source-Drain Diode						
Max. Diode Forward Current	I _S				1.6	A
Diode Forward Voltage	V _{SD}	I _S = 1.0A, V _{GS} = 0V			1.0	V

Notes

³⁾ Short duration test pulse used to minimize self-heating effect.

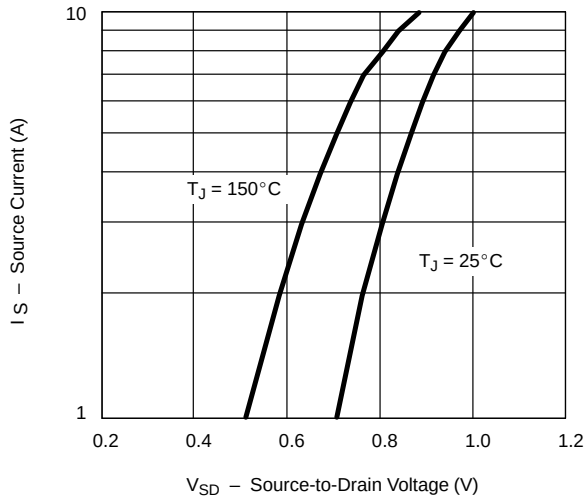
⁴⁾ Pulse test pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.



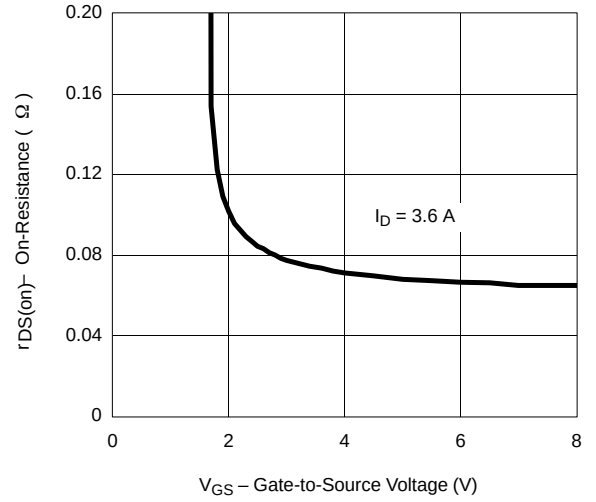




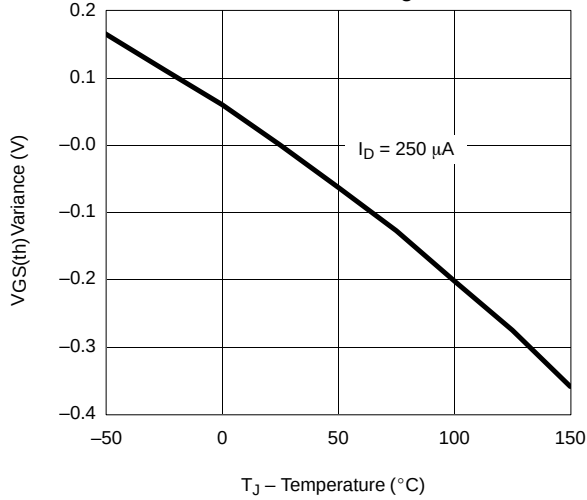
Source-Drain Diode Forward Voltage



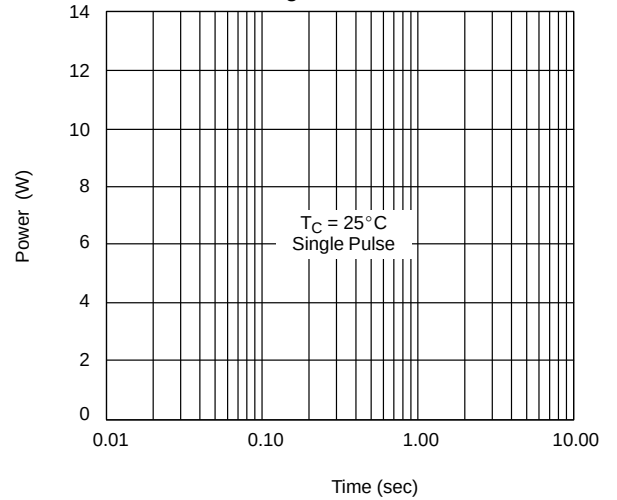
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power



Normalized Thermal Transient Impedance, Junction-to-Ambient

